



Your PDF Guides

You can read the recommendations in the user guide, the technical guide or the installation guide for KINGSTON KHX1866C9D3T1K36GX. You'll find the answers to all your questions on the KINGSTON KHX1866C9D3T1K36GX in the user manual (information, specifications, safety advice, size, accessories, etc.). Detailed instructions for use are in the User's Guide.

User manual KINGSTON KHX1866C9D3T1K36GX
User guide KINGSTON KHX1866C9D3T1K36GX
Operating instructions KINGSTON KHX1866C9D3T1K36GX
Instructions for use KINGSTON KHX1866C9D3T1K36GX
Instruction manual KINGSTON KHX1866C9D3T1K36GX

Kingston TECHNOLOGY *Memory Module Specification*

intel Core i7 **KHX1866C9D3T1K3/6GX**
6GB (2GB 256M x 64-Bit x 3 pcs.) DDR3-1866MHz
CL9 240-Pin DIMM Kit

DESCRIPTION:
Kingston's KHX1866C9D3T1K3/6GX is a kit of three 256M x 64-bit 2GB (2048MB) DDR3-1866MHz CL9 SDRAM (Synchronous DRAM) memory modules, based on sixteen 128M x 8-bit DDR3 FBGA components per module. Each module kit supports Intel® XMP (Extreme Memory Profiles). Total kit capacity is 6GB. Each module kit has been tested to run at DDR3-1866MHz at a low latency timing of 9-9-9 at 1.65V. The SPDs are programmed to JEDEC standard latency DDR3-1333MHz timing of 9-9-9 at 1.5V. Each 240-pin DIMM uses gold contact fingers and requires +1.5V. The JEDEC standard electrical and mechanical specifications are as follows:

FEATURES:

- JEDEC standard 1.5V ± 0.075V Power Supply
- VDDQ = 1.5V ± 0.075V
- 667MHz ICK for 1333Mbsocpin
- 8 independent internal bank
- Programmable CAS Latency: 5,6,7,8,9,10
- Posted CAS
- Programmable Additive Latency: 0, CL -2, or CL -1 clock
- Programmable CAS Write Latency (CWL) = 7 (DDR3-1333)
- 8-bit pre-fetch
- Burst Length: 8 (Interleave without any limit, sequential with starting address "00" only), 4 with rCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]
- Bi-directional Differential Data Strobe
- Internal self calibration - Internal self calibration through ZQ pin (RZQ: 240 ohm ± 1%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8us at lower than TCASE 85° C, 3.9us at 85° C < TCASE, 95° C
- Asynchronous Reset
- PCB : Height 2.401" (61.00mm) w/ heatsink, double sided component

PERFORMANCE:

- CL(I)DD) 9 cycles
- Row Cycle Time (RCmin) 49.5ns (min.)
- Refresh to Active/Refresh Command Time (RFCmin) 110ns
- Row Active Time (RASmin) 36ns (min.)
- Power 1.800 W (operating per module)
- UL Rating 94 V-0
- Operating Temperature 0° C to 85° C
- Storage Temperature -55° C to +100° C

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Manual abstract:

) DDR3-1866MHz CL9 240-Pin DIMM Kit DESCRIPTION: Kingston's KHX1866C9D3T1K3/6GX is a kit of three 256M x 64-bit 2GB (2048MB) DDR3-1866MHz CL9 SDRAM (Synchronous DRAM) memory modules, based on sixteen 128M x 8-bit DDR3 FBGA components per module. Each module kit supports Intel® XMP (Extreme Memory Profiles). Total kit capacity is 6GB. @@@@Each 240-pin DIMM uses gold contact fingers and requires +1.5V. @@@@4805279-001.A00 54.70 Page 2 .



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